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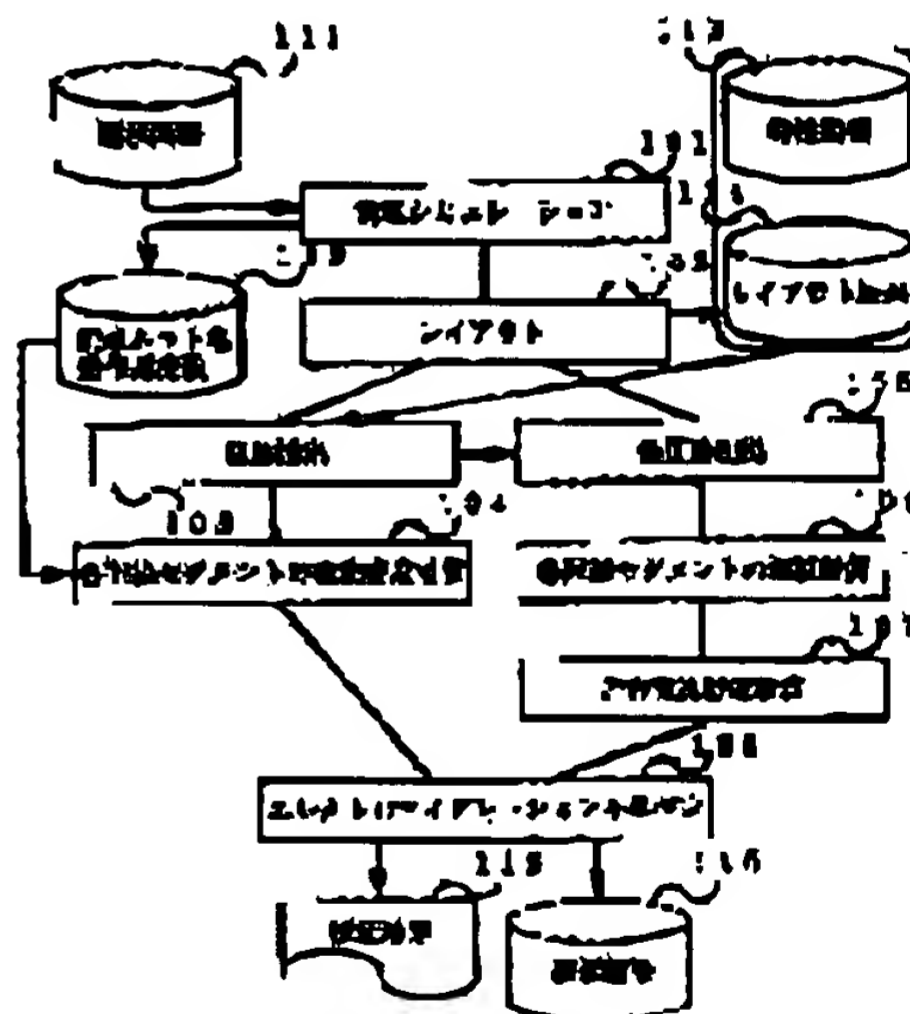
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(54) LAYOUT VERIFYING SYSTEM

(57)Abstract:

PROBLEM TO BE SOLVED: To quickly verify electromigration of a signal line while considering the temperature which is an important factor of electromigration.

SOLUTION: Results of circuit extraction 103 and each wiring (net) segment current density calculation 104 obtained from the operating frequencies of each wiring obtained in logical simulation 101 for a logic circuit and from the result of layout 102 operated based on the logic circuit is compared with the result of thermal circuit extraction 105, each wiring segment temperature calculation 106, and allowable current density calculation 107 obtained from the layout so that electromigration failure judgment 108 can be operated. Thus, the electromigration of a signal line can be quickly attained by considering temperature which is an important factor of the electromigration.



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